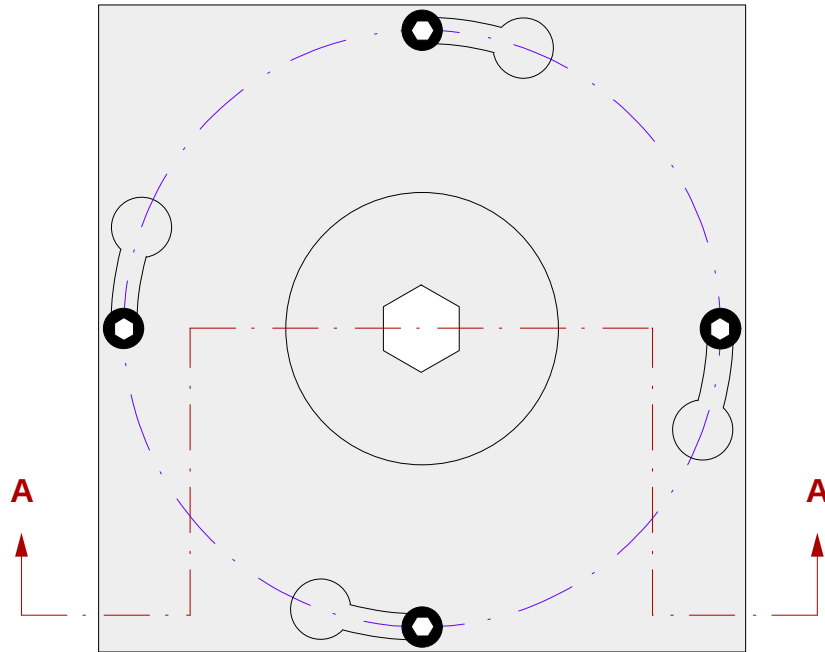
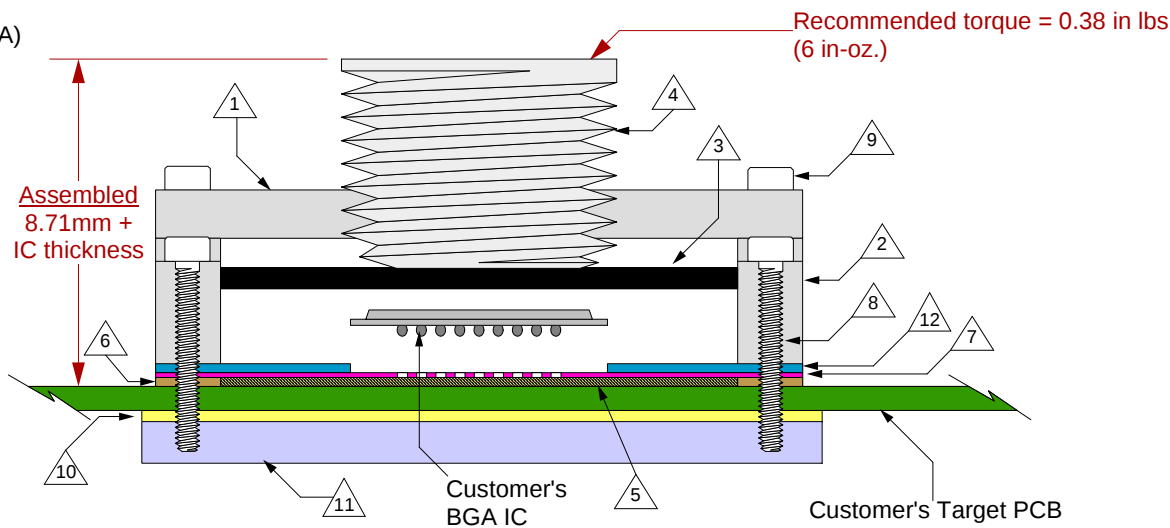


Top View



Side View
(Section AA)



GHz CSP Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid

- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.
- 12 IC Guide: FR4/G10

SG-BGA-7018 Drawing

Status: Released

Scale: -

Rev: E

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Tele: (952) 229-8200
www.ironwoodelectronics.com

Drawing: H. Hansen

Date: 5/21/03

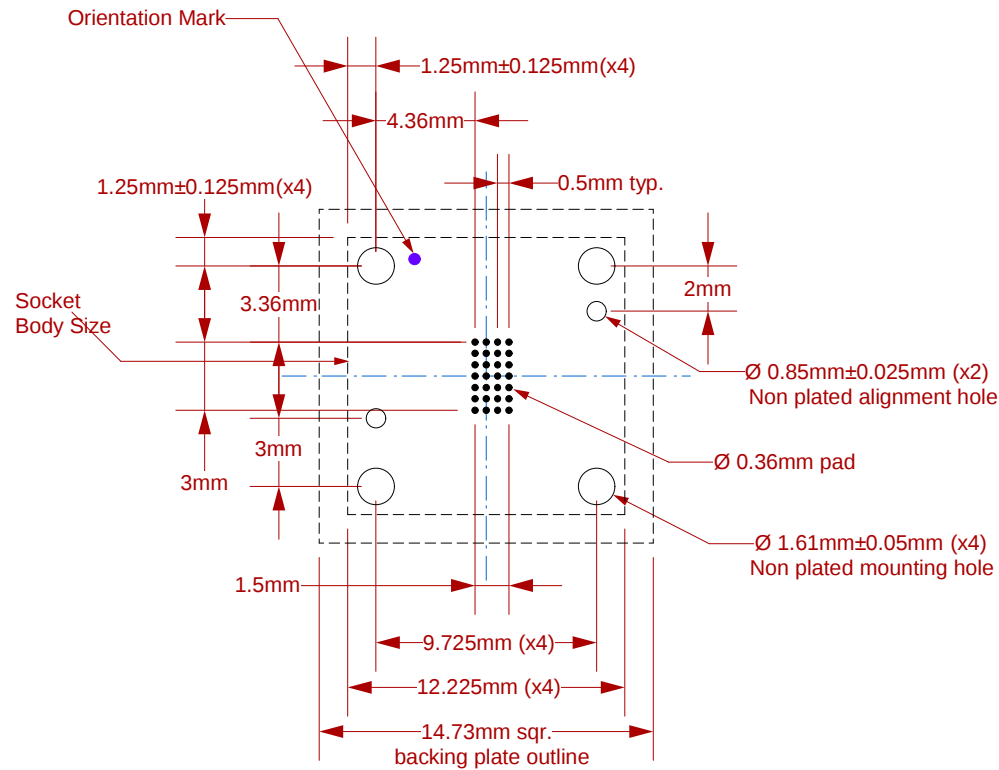
File: SG-BGA-7018 Dwg

Modified: 6/26/09, AE

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: CSP pattern is not symmetrical with respect to the mounting holes.**



Target PCB Recommendations

Total thickness: 1.6mm min.

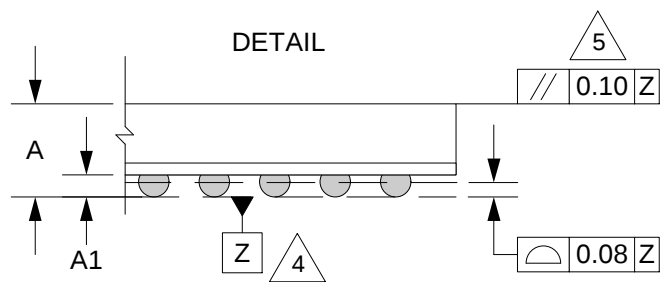
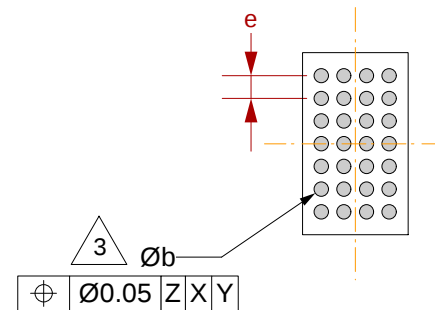
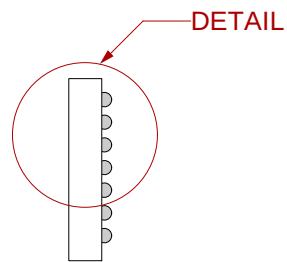
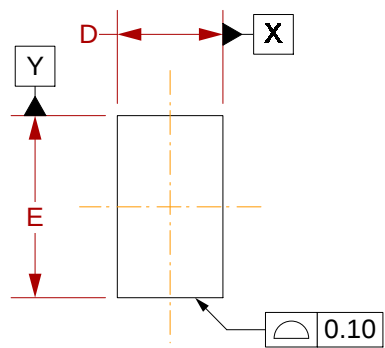
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001"$] unless stated otherwise.

SG-BGA-7018 Drawing	Status: Released	Scale: 3:1	Rev: E
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	File: SG-BGA-7018 Dwg	Modified: 6/26/09, AE	



1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

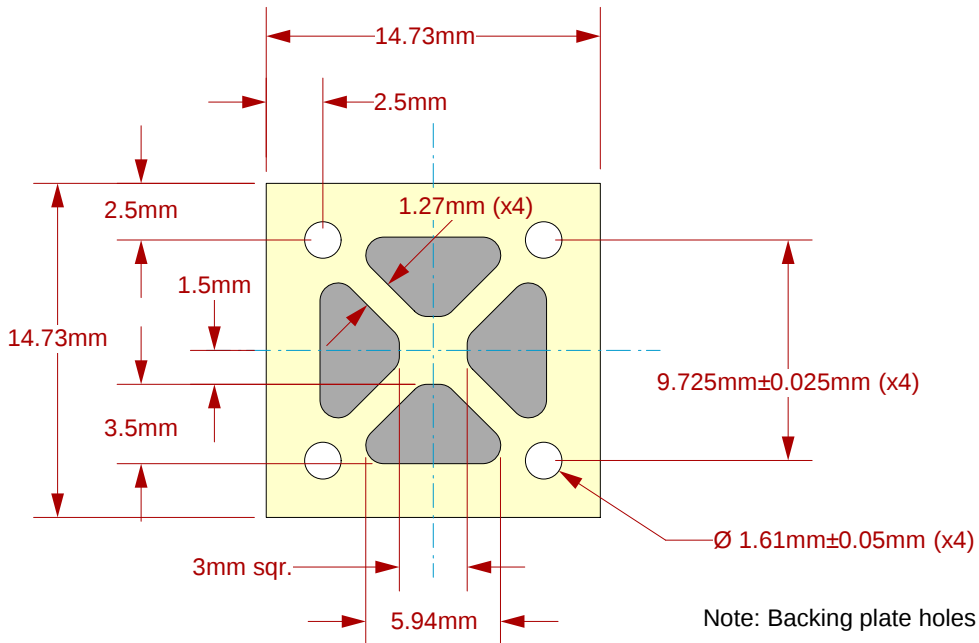
DIM	MIN	MAX
A		0.965
A1	0.195	0.225
b		0.315
D	2.326 BSC	
E	4.019 BSC	
e	0.5 BSC	

4 x 7 array

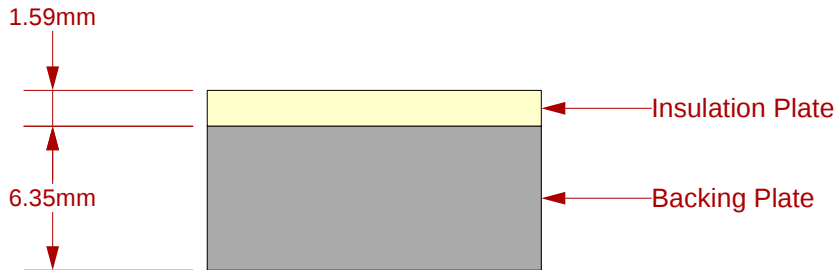
SG-BGA-7018 Drawing		Status: Released	Scale: -	Rev: E
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		File: SG-BGA-7018 Dwg		Modified: 6/26/09, AE

BOTTOM VIEW

Top View



Side View



Description: Insulation Plate and Backing Plate

SG-BGA-7018 Drawing		Status: Released	Scale: -	Rev: E
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	File: SG-BGA-7018 Dwg		Modified: 6/26/09, AE	

All dimensions are in mm.
All tolerances are $\pm 0.125\text{mm}$.
(Unless stated otherwise)